

SPECIFICATION FOR LCD MODULE

MODULE NO: AFK480272A1-4.3N12NTH REVISION NO: V02

Customer's Approval:

	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)		
CHECKED BY		
APPROVED BY		

Records of Revision

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2015-11-23		V01	First Issue	
2016-08-08		V02	Modify the drawing	

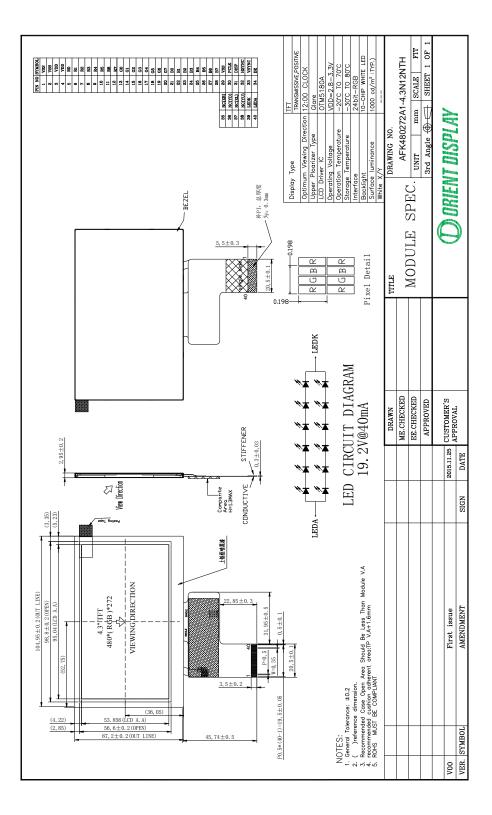
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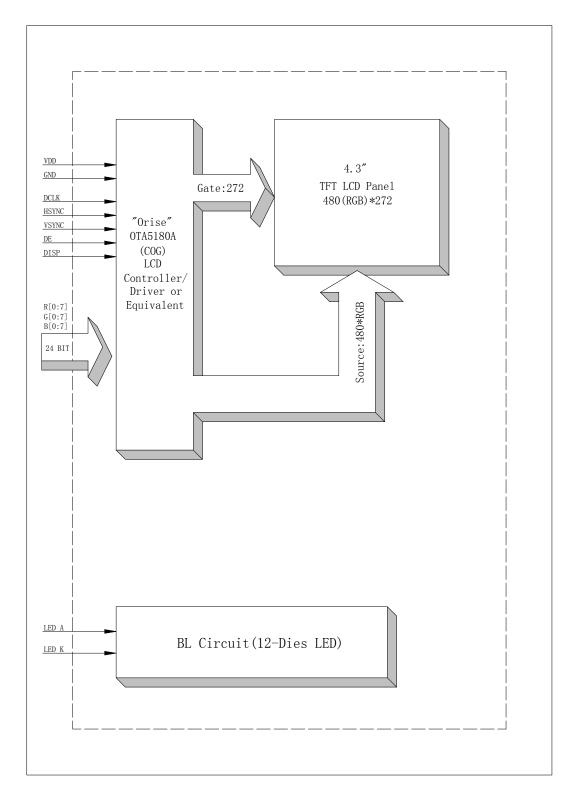
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	105.5*67.2*2.92	MM
ACTIVE SIZE (W*H)	95.04*53.865	MM
PIXEL PITCH (W*H)	0.198*0.198	MM
NUMBER OF DOTS	480*272	
DIVER IC	OTA5180A	
INTERFACE TYPE	24-BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	12	O'CLOCK
GRAY SCALE INVERSION DIRECTION	6	O'CLOCK
COLORS	16.7M	
BACKLIGHT TYPE	12- CHIP WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

NO.	SYMBOL	Description
1	VSS	Ground
2	VSS	Ground
3	VDD	Power supply
4	VDD	Power supply
5	R0	Data bus
6	R1	Data bus
7	R2	Data bus
8	R3	Data bus
9	R4	Data bus
10	R5	Data bus
11	R6	Data bus
12	R7	Data bus
13	G0	Data bus
14	G1	Data bus
15	G2	Data bus
16	G3	Data bus
17	G4	Data bus
18	G5	Data bus
19	G6	Data bus
20	G7	Data bus
21	B0	Data bus
22	B1	Data bus
23	B2	Data bus
24	B3	Data bus
25	B4	Data bus
26	B5	Data bus
27	B6	Data bus
28	B7	Data bus
29	VSS	Ground
30	PCLK	Pixel clock
31	DISP	Display on/off
32	HSYNC	Horizon YNC signal
33	VSYNC	Vertical YNC signal
34	DE	Data enable
35	NC	No connect

36	NC	No connect
37	NC	No connect
38	NC	No connect
39	LEDK	Cathode of LED back light
40	LEDA	Anode of LED back light

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.5	V
Supply voltage for logic	VDD	-0.3	4.5	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	Тор	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	3.0	3.3	3.6	V	
Supply Voltage for Logic	VDD	3.0	3.3	3.6	V	
Input Voltage	VIL	GND	-	0.3VDD	V	
Input Voltage	V _{IH}	0.7 VDD	-	VDD	v	
Input leakage Current	I _{LKG}	-1		1	μΑ	

6.2 Backlight Driving Conditions

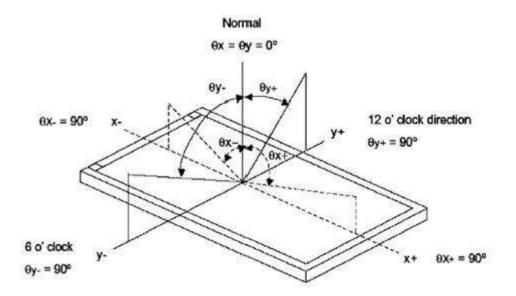
Itom	Sumbol		Value			Remar k	
Item	Symbol	Min. Typ. Max.		Unit			
Voltage for LED Backlight	VF	-	19.2	-	V	$I_L = 40 \text{mA}$	
Current for LED Backlight	IL		40		mA		
Power Consumption	Р		0.768		W		
LED Life Time		30,000			Hr	Note	

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}$ C

7. Optical Characteristics

	.		CONDITIONS	SPEC	IFICA	ΓΙΟΝS		NOTE
ITEM		SYMBOL	MBOL CONDITIONS		TYP.	MAX	UNIT	NOTE
Lumina	Luminance		$I_L = 40 \text{mA}$		1000		Cd/m ²	
Contrast l	Ratio	CR	θ=0°	250	350			
Response	Timo	Ton	25 ℃		30	45	ma	
Kesponse	1 mile	Toff	250	-	50	43	ms	
	Red	Xr						
	Keu	Yr						
	Green	XG						
CIE Color		YG	Viewing normal					
Coordinate		Хв	angle					
		Үв						
	White	Xw			-			
	white	Yw			-			
	Hor.	$ heta_{X+}$		55	65		Degree	
Viewing	1101.	$ heta_{_{X-}}$	CR≥10	55	65			
Angle	Ver.	$ heta_{_{Y+}}$	CK=10	45	55			
		$ heta_{_{Y-}}$		45	55			
Uniformity	Un			80			%	

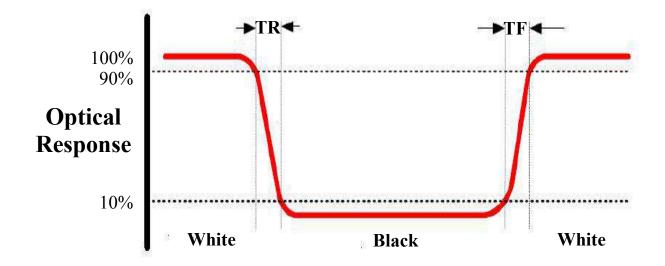
Note 1: Definition of Viewing Angle θx and θy:



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

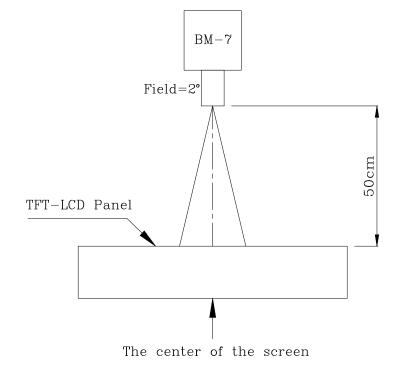




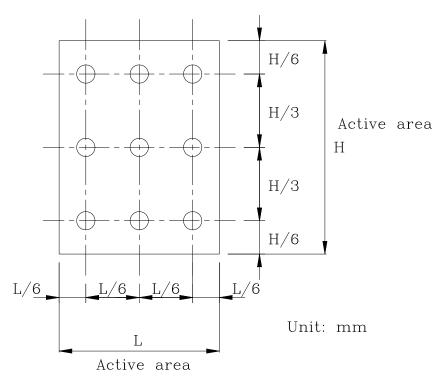
Note 4: Definition of Luminance

①The Brightness Test Equipment Setup

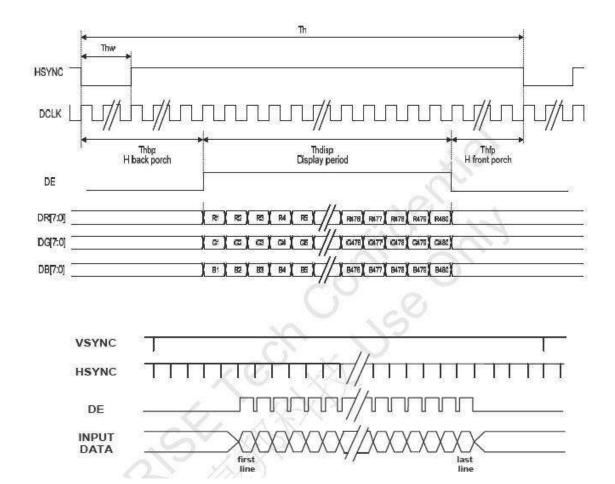
Field= 2° (As measuring "black" image, field= 2° is the best testing condition)



②The Brightness Test Point Setup

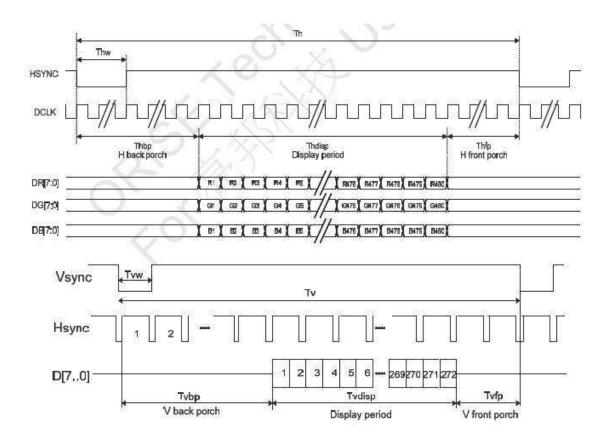


8. Timing Characteristics



8.1 SYNC-DE Mode Timing Diagram

8.2 SYNC Timing Diagram



8.3 Parallel Timing table

Item DCLK Frequency		Symbol	Min.	Тур.	Max.	Unit	
		Fclk	5	9	12	MHz	
DCLK F	Period	Tclk	83	110	200	ns	
Hsync	Period Time	Th	490	531	605	DCLK	4
	Display Period	Thdisp		480		DCLK	-
	Back Porch	Thbp	8	43		DCLK	By H_BLANKING setting
	Front Porch	Thfp	2	8		DCLK	
15	Pulse Width	Thw	1		ia l	DCLK	1
Vsync	Period Time	Tv	275	288	335	Н	
	Display Period	Tvdisp	i.	272		Н	100
	Back Porch	Tvbp	2	12	X	Н	By V_BLANKING setting
	Front Porch	Tvfp	્ય	4	0	н	1
	Pulse Width	Tvw	1	10		н	

8.4 Power ON/OFF Sequence

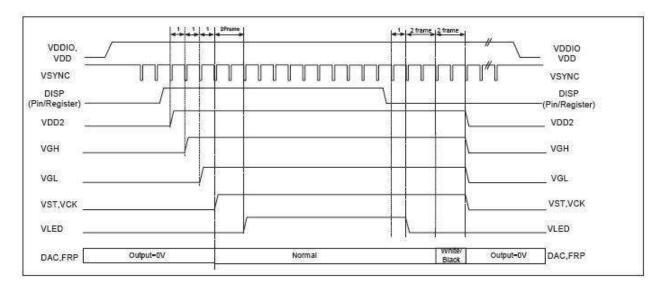


Fig. Power Sequence

Note:

a. When MVA mode (Normally black LC) is applied, it needs to send black pattern to discharge the pixel.

b. When TN_MODE2 or TN_MODE1 mode (Normally white LC) is applied, it needs to send white pattern to discharge the pixel.

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80° C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30° C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10 Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
09	Electrical Static	Air: ±4KV 150pF/330Ω 5 times
09	Discharge	Contact: ± 2 KV 150pF/330 Ω 5 time

*Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature $(25\pm5^{\circ}C)$, normal humidity $(50\pm10\%$ RH), and in area not exposed to direct sun light.

10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by OD.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following: Major defect: AQL = 0.40 Minor defect: AQL = 0.65 Total defects: AQL = 0.40

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

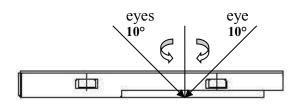
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

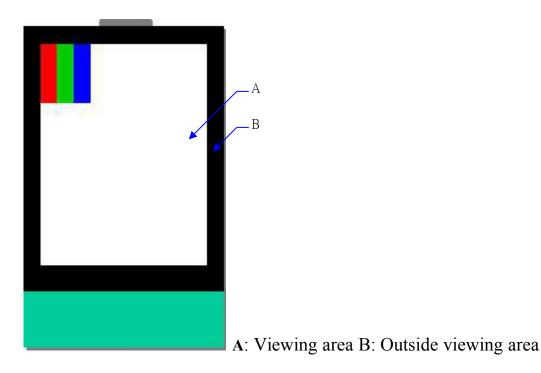
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



• Definition of area:



10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion				
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 				2.5
03	LCD and Touch Panel black spots, white spots, contaminati on (non – display)	3.1 Round type: As follo $\Phi = (X+Y) / 2$ \downarrow		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.35 < \Phi$	Acceptable Q'ty Accept no dense 2 1 0 70 spots within 3mm.	2.5
		3.2 Line type: (As follow M L M L	Length(mm) L≤4.0	Width(mm) W ≤ 0.03 0.03 < W ≤ 0.05 0.05 < W	Acceptable Q'ty Accept no dense	2.5

NO.	Item	Criterion					
04	Polarizer	If bubbles are visible, judge using black spot		$p \le 0.10$	Acceptable Q'ty Accept no	_	
		specifications, not easy to find, must check in		$< \Phi \le 0.25$	dense 2	2.5	
	bubbles	specify direction		= 0.23 = 0.30	<u> </u>		
				= 0.30 $= 0.35 < \Phi$	0		
				otal Q'ty	3	_	
05	Scratches	Follow NO.3 -2 Line Type.					
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:Image: Chip of panel surface and crack between panels:Image: Chip thickness zy: Chip width xx: Chip length reaZ: Chip thickness zy: Chip width areax: Chip length reaImage: Chip thickness zy: Chip width areax: Chip length reaImage: Chip thickness zy: Chip width areax: Chip length reaImage: Chip thickness ty: Chip width areax: Chip length reaImage: Chip thickness ty: Chip width areax: Chip length 			2.5		

NO.	Item	Criterion	
08	Cracked glass	The LCD with extensive crack is not acceptable.	
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	
10	Bezel	Bezel must comply with product specifications.	
11	РСВ、СОВ	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	
12	FPC	12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function, we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion				
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:				
		y: Chip width x: Chip length z: Chip thickness				
		$y \le 0.5$ mm $x \le 1/8a$ $0 < z \le t$				
07	Glass crack	7.2.2 Non-conductive portion: y y z z y z z x z	2.5			
		y: Chip width x: Chip length z: Chip thickness				
		$y \le L$ $x \le 1/8a$ $0 < z \le t$				
○ If there chipped area touches the ITO terminal, over 2/3 of the IT must remain and be inspected according to electrode terminal specifications. ○ If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack x y						

NO.	Item	Criterion				
14	Touch Panel Chipped glass	 k: Seal width t: T L: Electrode pad leng 14.1 General glass cl 14.1.1 Chip on panel Z ≤ t O Unit: mm 	gth hip: surface and crack betwo x y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length $x \le 1/8a$	2.5	
		z: Chip thickness	y: Chip width	x: Chip length		
		z≦t	$\leq 1/2$ k and not over viewing area	$x \leq 1/8a$		
	 Unit: mm If there are 2 or more chips, x is the total length of each chip 					

NO.	Item	Criterion		
15	Touch Panel(Fish eye、dent and bubble on film)	SIZE(mm)Acceptable Q'ty $\Phi \le 0.1$ Accept no dense $0.1 < D \le 0.25$ 2 $0.25 < D \le 0.30$ 1 $0.35 < D$ 0	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.		
17	Touch Panel Linearity	Less than 2.5% is acceptable.		
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 		

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD